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(54) Title: LOW DISHING COPPER CHEMICAL MECHANICAL PLANARIZATION

(57) Abstract: Copper chemical mechanical planarization (CMP) polishing formulation, method and system are disclosed. The CMP polishing formulation comprises abrasive particles of specific morphology and mean particle sizes (≤ 100 nm, ≤ 50 nm, ≤ 40 nm, ≤ 30 nm, or ≤ 20 nm), at least two or more amino acids, oxidizer, corrosion inhibitor, and water.

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